

ABSTRACT OF THE DISCLOSURE

What is disclosed is a 2-part epoxy adhesive composition comprises an epoxy compound, an optional amine hardener, optional hydroxy-substituted aromatic compound, and from 20% to 60% of the total weight of adhesive combined of liquid terminal epoxy reactive groups and amidoamine, whereby the adhesive is applied as a mixture of first and second parts in a volume ratio of the first epoxy part : second cure part of 1:1.4 to 1:3.0. The adhesive is adapted to provide bonding of SMC with low or no read-through, initial and aged fiber tearing bonds and specified bond strength minimum at 400°F (204°C).